



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

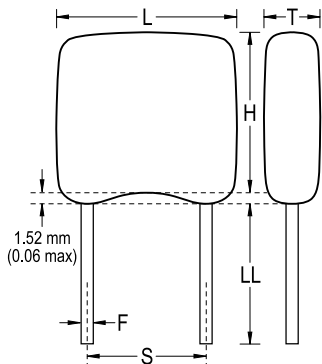
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GoldMax 300 Comm X7R, Ceramic, 2700 pF, 10%, 100 VDC, X7R, GoldMax, Commercial Standard, Lead Spacing = 2.54mm



General Information	
Supplier:	KEMET
Series:	GoldMax 300 Comm X7R
Style:	Radial
Description:	GoldMax, Commercial Standard
RoHS:	Yes
Termination:	Tin
Failure Rate:	N/A
Halogen Free:	Yes

Dimensions	
L	3.81mm MAX
H	3.14mm MAX
T	2.54mm MAX
S	2.54mm +/-0.78mm
LL	7mm MIN
F	0.51mm +0.1/-0.025mm

Specifications	
Capacitance:	2700 pF
Capacitance Tolerance:	10%
Voltage DC:	100 VDC
Dielectric Withstanding Voltage:	250 V
Temperature Range:	-55/+125C
Temperature Coefficient:	X7R
Dissipation Factor:	2.50% 25C
Aging Rate:	3% Loss/Decade Hour
Insulation Resistance:	100 GOhms

Packaging Specifications	
Packaging:	Bulk, Bag
Packaging Quantity:	500